Amendments to the Specification:

Please replace the title of the invention to the following revised title:

--METHOD~~, APPARATUS, SYSTEM, METHOD AND DEVICE FOR DATA CREATING, AND PROGRAM~~ FOR MOUNTING AN ELECTRONIC COMPONENT--

Please replace the paragraph on page 28, lines 12-19, with the following revised paragraph:

--Fig. 23 is a view showing an example of a structure according to a first variant of an electronic component mounting system for implementing the electronic component mounting method according to each embodiment. Fig. 24 is a view showing an example of a structure according to a second variant of the electronic component mounting system for implementing the electronic component mounting method according to each embodiment.--

Please replace the paragraph on page 29, lines 3-4, with the following revised paragraph:

--~~Fig. 28 is a diagram~~ Figs. 28(a) through 28(c) are diagrams showing results obtained by comparing self-alignment effects on two conditions.--

Please replace the paragraph beginning on page 31, line 14, and ending on page 32, line 12, with the following revised paragraph:

--As shown in Fig. 2, solder pastes 16a and 16b are printed on lands 14a and 14b formed on a circuit board 12 in a

position shifted from a land center line L1 by a distance ΔL. In this case, an electronic component 18 is mounted in alignment with the positions of the solder pastes 16a and 16b and a center line Lc of the solder pastes 16a and 16b is almost coincident with a center line Lp of the electronic component. When the reflow process is carried out in this state, the solder paste is molten and fluidized over the land. In the early stage of the fluidization, a solder 20 extensively wets due to "immersion wetting" which is generally caused during capillary permeation as shown in Fig. 3(a). When the solder 20 extensively wets both end faces 18a and [[18a]] 18a' of the electronic component 18 as shown in Fig. 3(b), the "extension wetting" of the solder on the component end face side is stopped and only the solder on the land 14 side extensively wets. Consequently, the solder 20 moves the electronic component 18 in the direction of an arrow to bring a stable state having a dynamic balance. This acts as the self-alignment effect so that the electronic component 18 is finally provided in such a position that the center line L1 of the land 14 is coincident with the center line Lp of the electronic component 18 as shown in Fig. 3(c).--

Please replace the paragraph beginning on page 36, line 13, and ending on page 37, line 10, with the following revised paragraph:

--Next, the structure of the inspecting apparatus 200 will be described. Fig. 8 is a perspective view showing the appearance of the structure of the inspecting apparatus 200, a part of which is taken away. The inspecting apparatus 200 includes a printing position detecting device for detecting the printing position of the solder paste printed on the circuit board. The inspecting apparatus 200 includes a board delivering portion 40 for delivering the circuit board [[10]] 12 thus fed, light sources 44 and 44 such as fluorescent lamps for illuminating the circuit board 12 stationary in a inspecting unit 42 in an oblique direction, and an image pick-up camera 46 for picking up the image of a board surface from above the circuit board 12. In the inspecting apparatus 200, the image of the circuit board 12 illuminated by the light sources 44 and 44 is picked up by the image pick-up camera 46 and the image thus picked up is processed by a controller (not shown) provided in the inspecting apparatus 200. Consequently, each land of the circuit board 12 and the printed solder paste are detected to obtain a corresponding shift amount thereof. Information about the shift amount thus obtained is once retained in the controller and is transmitted as a